Title (en)

MEDIA-TIGHT INSERT MOLDING OF ELECTRONICS CIRCUIT BOARDS WITH EXTERNAL CONTACTING

Title (de)

MEDIENDICHTES UMSPRITZEN VON ELEKTRONIKPLATINEN MIT AUßENKONTAKTIERUNG

Title (fr)

ENROBAGE ÉTANCHE AUX FLUIDES DE CARTES DE CIRCUITS IMPRIMÉS ÉLECTRONIQUES AVEC MISE EN CONTACT EXTÉRIEURE

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Application

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Abstract (en)

[origin: WO2022243134A1] The invention relates to a printed circuit board arrangement (100) comprising a printed circuit board (1), the board surface of which extends horizontally and which comprises a vertical top side and underside, wherein it has a planar component portion with at least one electronics component (3), in particular a plurality of electronics components (3), arranged thereon, wherein the component portion is enclosed in sealed fashion in a plastics protective layer. A top-side delimitation conductor track is arranged on the top side of the printed circuit board (1) and, across a conductor track length, extends with a conductor track width on the top side and, across its conductor track length, divides the top side into two top-side regions that are completely and uninterruptedly separated from one another, wherein a first of said top-side regions is formed by the component portion and a second of said top-side regions is formed by a planar contact portion of the printed circuit board (1), which is arranged in portions outside the plastics protective layer (2), wherein the top-side delimitation conductor track, uninterruptedly across its conductor track length, is arranged at least with a part of its conductor track width within the plastics protective layer (2) and is sealingly connected thereto, wherein an adhesion promoter is applied in particular to the top-side delimitation conductor track (41) across the conductor track length thereof and ensures a sealing connection between the plastics protective layer (2) and the delimitation conductor track (41).

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